Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Characteristic			Symbol	Value	Units
Drain-Source Voltage			V_{DSS}	30	V
Gate-Source Voltage			V_{GSS}	±25	V
Continuous Drain Current (Note 5) V_{GS} = 10V	Steady State	T_A = +25°C T_A = +70°C	I_D	5.3 4.2	A
	t<10s	T_A = +25°C T_A = +70°C	I_D	6.8 5.2	A
Continuous Drain Current (Note 6) V_{GS} = 10V	Steady State	T_A = +25°C T_A = +70°C	I_D	8.6 6.8	A
	t<10s	T_A = +25°C T_A = +70°C	I_D	11 8.8	A
Pulsed Drain Current (10µs pulse, duty cycle = 1%)			I_{DM}	70	A
Maximum Body Diode continuous Current			I_S	3	A

Thermal Characteristics

Characteristic		Symbol	Value	Units
Total Power Dissipation (Note 5)	T_A = +25°C	P_D	0.9	W
	T_A = +70°C		0.5	
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	$R_{\theta JA}$	148	°C/W
	t<10s		89	
Total Power Dissipation (Note 6)	T_A = +25°C	P_D	2.3	W
	T_A = +70°C		1.4	
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	$R_{\theta JA}$	56	°C/W
	t<10s		34	
Thermal Resistance, Junction to Case (Note 6)		$R_{\theta JC}$	6.9	
Operating and Storage Temperature Range		T_J, T_{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	30	—	—	V	V_{GS} = 0V, I_D = 250µA
Zero Gate Voltage Drain Current T_J = +25°C	I_{DSS}	—	—	100	nA	V_{DS} = 30V, V_{GS} = 0V
Gate-Source Leakage	I_{GSS}	—	—	±1	µA	V_{GS} = ±25V, V_{DS} = 0V
		—	—	100	nA	V_{GS} = ±20V, V_{DS} = 0V
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	0.8	1.2	2.1	V	V_{DS} = V_{GS}, I_D = 250µA
Static Drain-Source On-Resistance	$R_{DS\ (ON)}$	—	10	18	mΩ	V_{GS} = 10V, I_D = 10A
		—	16	27		V_{GS} = 4.5V, I_D = 7.5A
Forward Transfer Admittance	$\|Y_{fs}\|$	—	6	—	S	V_{DS} = 5V, I_D = 10A
Diode Forward Voltage	V_{SD}	—	0.7	1.0	V	V_{GS} = 0V, I_S = 1A
DYNAMIC CHARACTERISTICS (Note 8)						
Input Capacitance	C_{iss}	—	751	—	pF	V_{DS} = 10V, V_{GS} = 0V, f = 1.0MHz
Output Capacitance	C_{oss}	—	121	—		
Reverse Transfer Capacitance	C_{rss}	—	110	—		
Gate Resistance	R_g	—	1.5	—	Ω	V_{DS} = 0V, V_{GS} = 0V, f = 1MHz
Total Gate Charge V_{GS} = 4.5V	Q_g	—	9	—	nC	V_{GS} = 4.5V, V_{DS} = 15V, I_D =6A
Total Gate Charge V_{GS} = 10V	Q_g	—	17.4	—		V_{GS} = 10V, V_{DS} = 15V, I_D = 6A
Gate-Source Charge	Q_{gs}	—	2.2	—		
Gate-Drain Charge	Q_{gd}	—	3	—		
Turn-On Delay Time	$t_{D(on)}$	—	2.5	—	ns	V_{DD} = 15V, V_{GS} = 10V, R_G = 6Ω, R_L = 1.8Ω, I_D = 6.7A
Turn-On Rise Time	t_r	—	6.6	—		
Turn-Off Delay Time	$t_{D(off)}$	—	19.0	—		
Turn-Off Fall Time	t_f	—	6.3	—		

Notes:
5. Device mounted on FR-4 PCB with minimum recommended pad layout, single sided.
6. Device mounted on FR-4 substrate PC board, 2oz copper, with thermal vias to bottom layer 1inch square copper plate.
7. Short duration pulse test used to minimize self-heating effect.
8. Guaranteed by design. Not subject to production testing.

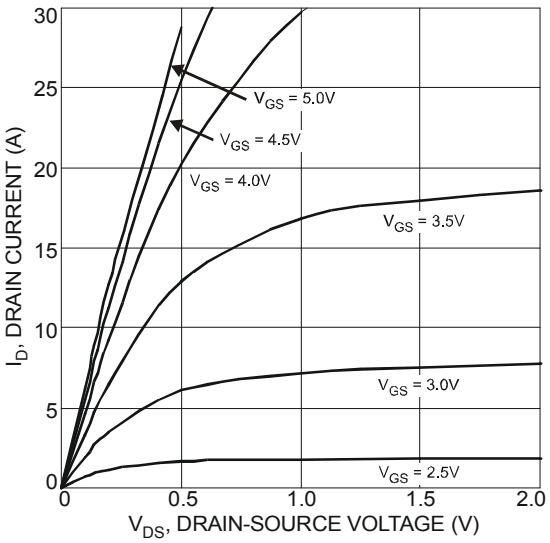


Fig.1 Typical Output Characteristic

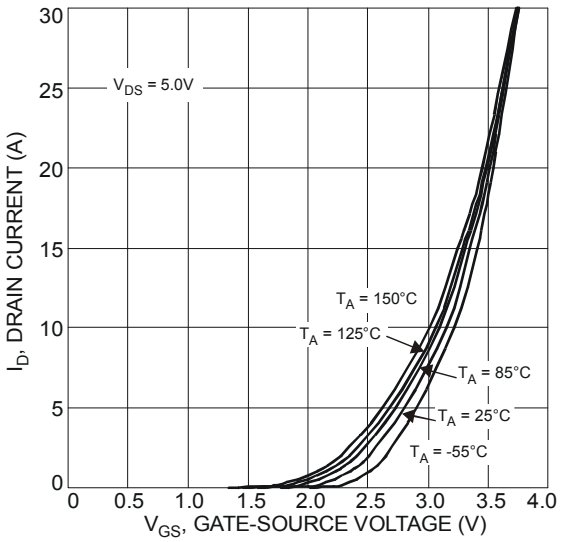


Fig. 2 Typical Transfer Characteristics

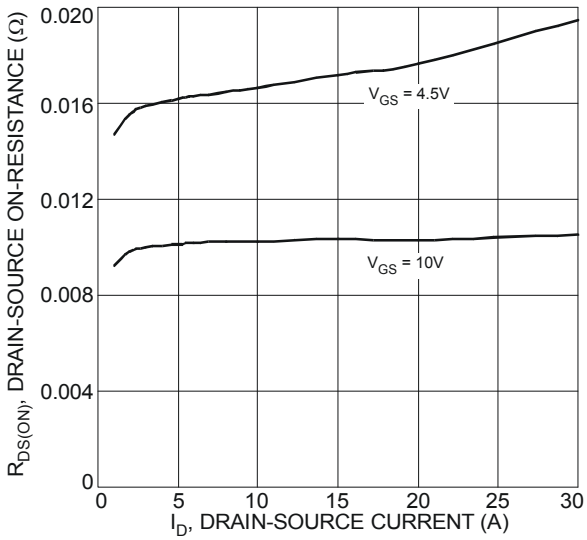


Fig. 3 Typical On-Resistance vs. Drain Current and Gate Voltage

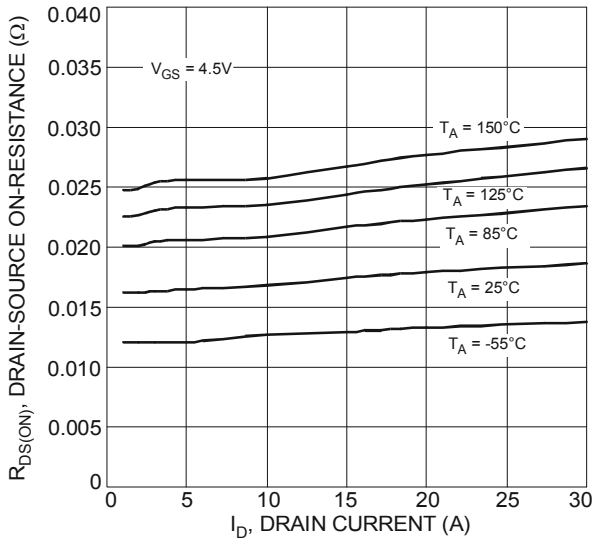


Fig. 4 Typical On-Resistance vs. Drain Current and Temperature

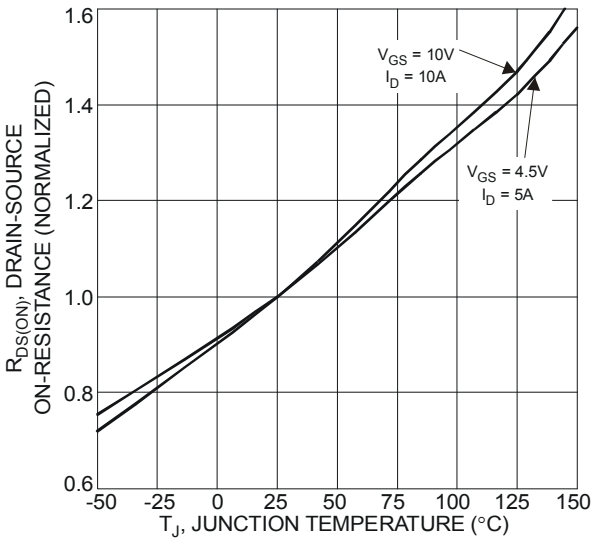


Fig. 5 On-Resistance Variation with Temperature

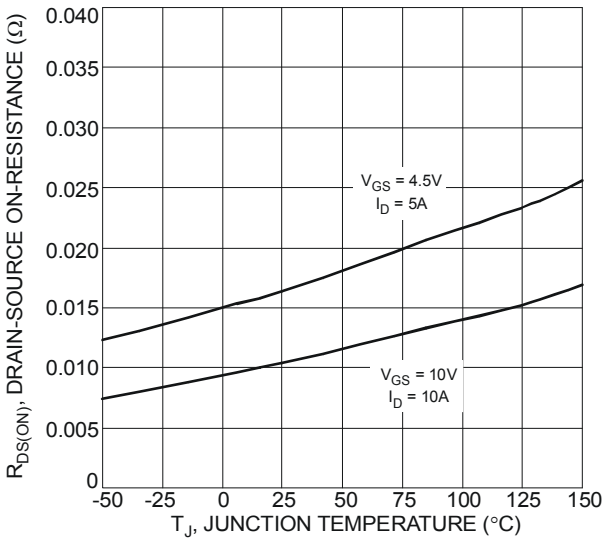


Fig. 6 On-Resistance Variation with Temperature

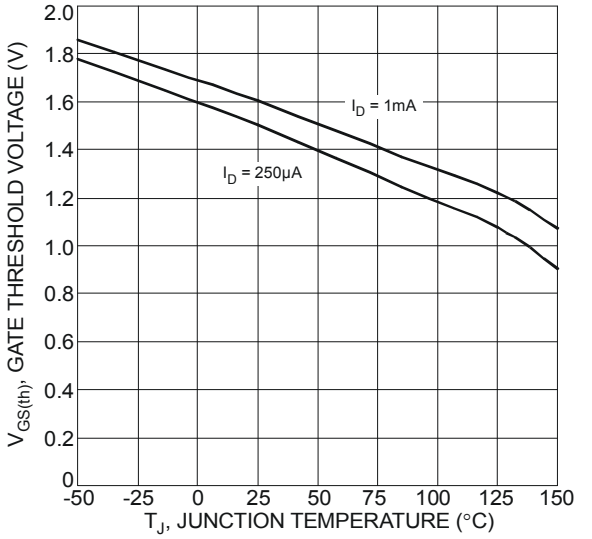


Fig. 7 Gate Threshold Variation vs. Ambient Temperature

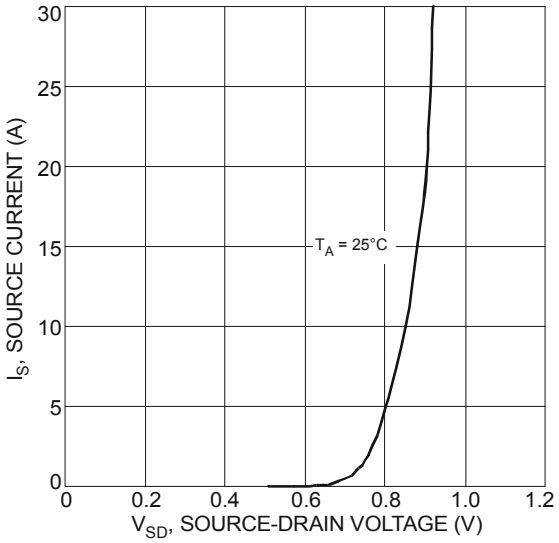


Fig. 8 Diode Forward Voltage vs. Current

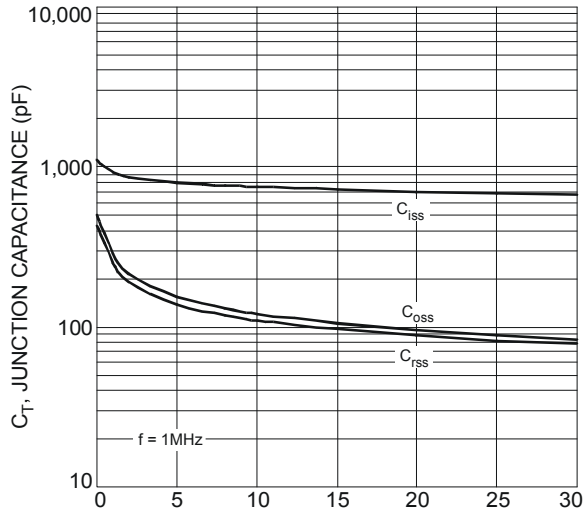


Fig. 9 Typical Junction Capacitance

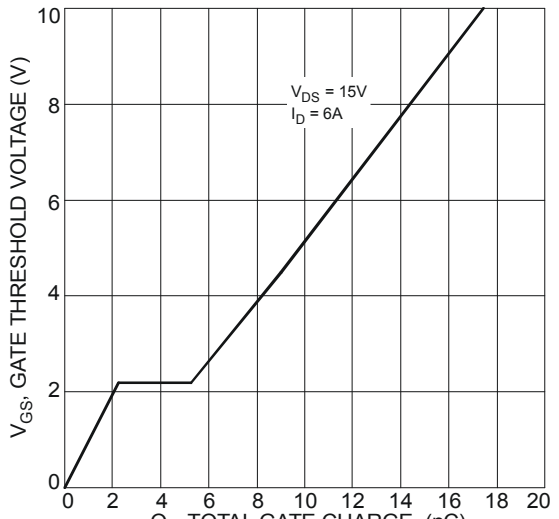


Fig. 10 Gate Charge

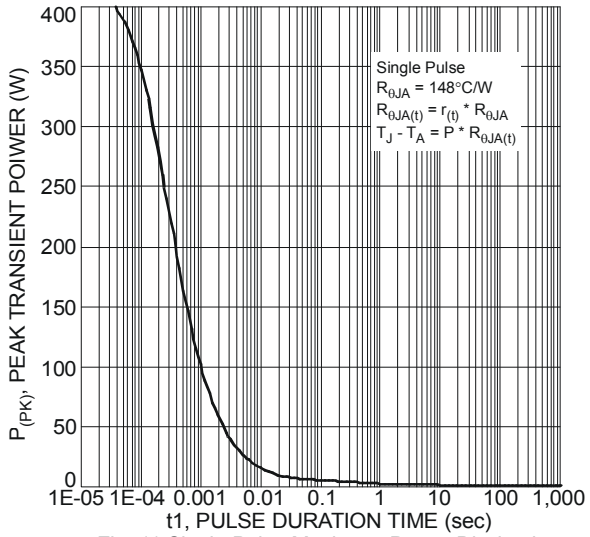


Fig. 11 Single Pulse Maximum Power Dissipation

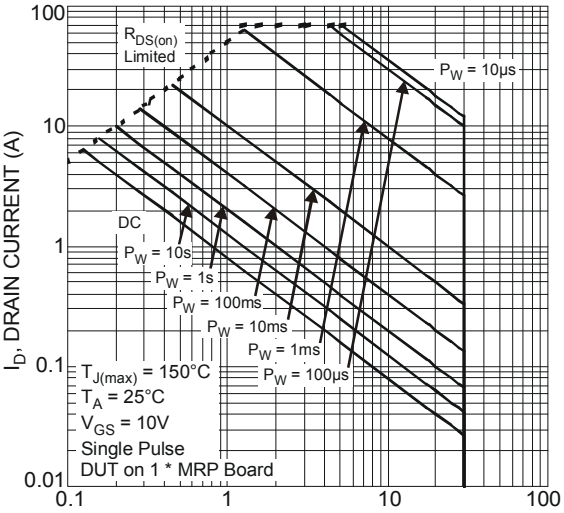


Fig. 12 SOA, Safe Operation Area

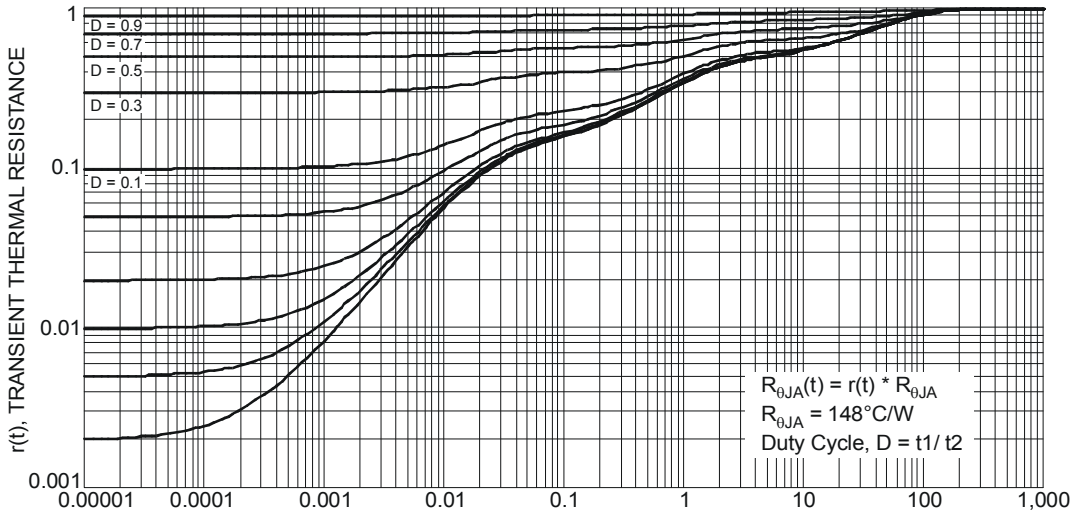
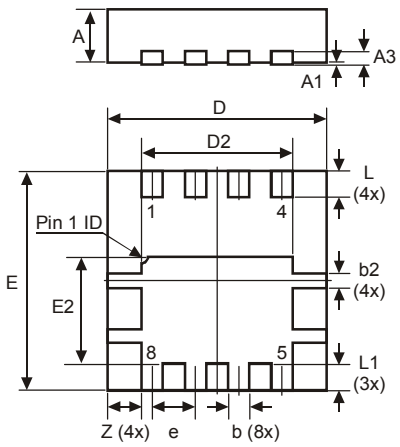


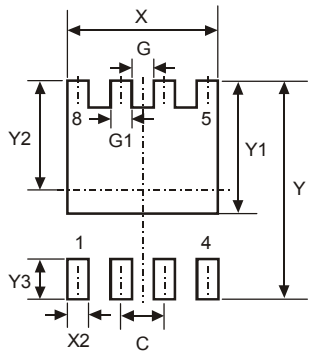
Fig. 13 Transient Thermal Resistance

Package Outline Dimensions



POWERDI®3333-8			
Dim	**Min**	**Max**	**Typ**
D	3.25	3.35	3.30
E	3.25	3.35	3.30
D2	2.22	2.32	2.27
E2	1.56	1.66	1.61
A	0.75	0.85	0.80
A1	0	0.05	0.02
A3	-	-	0.203
b	0.27	0.37	0.32
b2	-	-	0.20
L	0.35	0.45	0.40
L1	-	-	0.39
e	-	-	0.65
Z	-	-	0.515
All Dimensions in mm			

Suggested Pad Layout



Dimensions	Value (in mm)
C	0.650
G	0.230
G1	0.420
Y	3.700
Y1	2.250
Y2	1.850
Y3	0.700
X	2.370
X2	0.420

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